

6. (Amended) The wiring board according to claim 1,
wherein the substrate is formed on at least one surface of a core substrate; and
an opening is formed so as to penetrate at least one of said core substrate and said build-up layer,
wherein said electronic component is placed in the opening and embedded ⁱⁿ by means of said embedding resin.

Please add new claim 7 as follows:

7. (New) A wiring board comprising:
an embedding resin having a dielectric constant of less than or equal to about 5 and $\tan\delta$ of less than or equal to about 0.08;
an electronic component being embedded in said embedding resin; and
a substrate on said embedding resin, said substrate including a laminated build-up layer of alternating insulating and wiring layers.